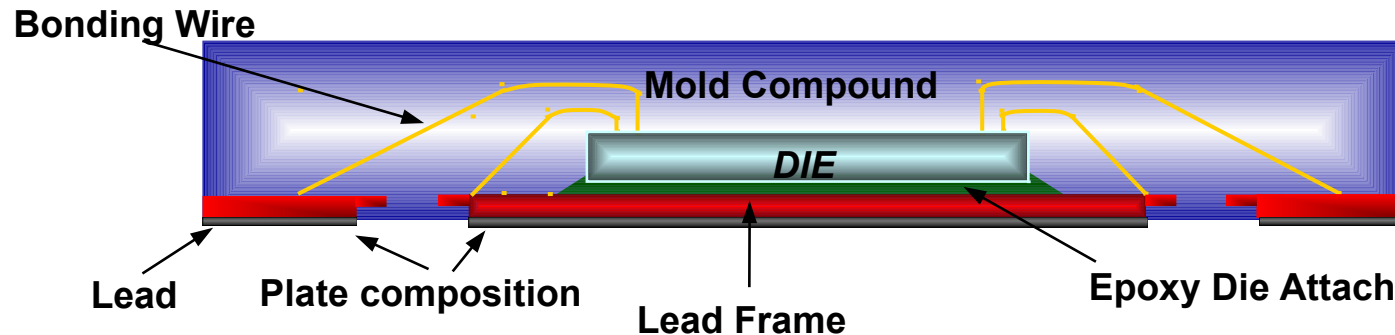


Doc: C
Rev: 1

Cross-Section View VS1205G/VS1005G 88pin QFN (ROHS)



SUBSTRATE (Lead Frame)

Plate composition

Sn 100%

Plate thickness

200~1000 micro inches

Material

Lead Frame

C194 (FH)

Epoxy Die Attach

AP4200

Bonding Wire

Pd coated Copper wire 0.8 MIL

Mold Compound

EME G770HC